

## Patent Abstracts of Japan

PUBLICATION NUMBER : 2000306951  
PUBLICATION DATE : 02-11-00

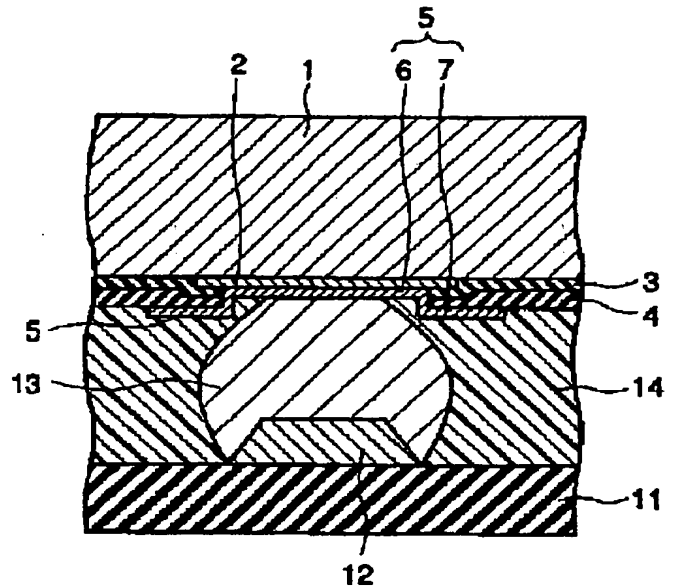
APPLICATION DATE : 19-04-99  
APPLICATION NUMBER : 11110461

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INT.CL. : H01L 21/60 H01L 21/28 H01L 21/3205  
H01L 21/768 H01L 27/04 H01L 21/822

TITLE : SEMICONDUCTOR DEVICE AND  
MANUFACTURE THEREOF



**ABSTRACT :** **PROBLEM TO BE SOLVED:** To obtain a semiconductor device, having such a structure as to allow a semiconductor substrate with pads arranged at narrow intervals to be mounted on an insulating circuit board, while ensuring insulating properties, and a manufacturing method therefor.

**SOLUTION:** This semiconductor device comprises an electrode pad 2 formed on a semiconductor substrate 1, a connecting base metal film 5 to be connected to the pad 2, a connecting conductor 13 electrically connected between the film 5 and a terminal electrode 12 on an insulating circuit substrate 11, and a non-conductive resin 14 for covering the region around the conductor 13 and embedding clearances between both the substrates. The film 5 is such, that at least a peripheral region thereof including the outermost edge is not covered with the conductor 13.

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